

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 7,056,766 B2

APPLICATION NO. : 10/731831

Page 1 of 1

DATED : ~~May 20, 2008~~ June 6, 2006

INVENTOR(S) : Hei Ming Shiu

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In Column 7, Line 11, Claim No. 14:

Change "dice, comprising" to --die, comprising--

In Column 7, Line 18, Claim No. 14:

Change "dice to the mold" to --die to the mold--

In Column 7, Line 19, Claim No. 14:

Change "of the dice have" to --of the die have--

In Column 7, Line 22, Claim No. 14:

Change "of the dice to" to --of the die to--

In Column 7, Line 24, Claim No. 14:

Change "dice;" to --die;--

In Column 7, Line 25, Claim No. 14:

Change "encapsulating the dice," to --encapsulating the die,--

In Column 7, Line 28, Claim No. 14:

Change "such that a bottom" to --such that bottom--

In Column 7, Line 30, Claim No. 14:

Change "encapsulated dice to" to --encapsulated die to--

In Column 8, Line 14, Claim No. 20:

Change "wherein the dice" to --wherein the die--

In Column 8, Line 15, Claim No. 20:

Change "side of the dice" to --side of the die--

This certificate supersedes certificate of correction
issued May 20, 2008.

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